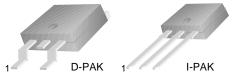


### **KSH210**

### **D-PAK for Surface Mount Applications**

- High DC Current Gain
- Low Collector Emitter Saturation Voltage
- Lead Formed for Surface Mount Applications (No Suffix)
- Straight Lead (I-PAK, " I " Suffix)



1.Base 2.Collector 3.Emitter

### **PNP Epitaxial Silicon Transistor**

### Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CBO</sub>	Collector-Base Voltage	- 40	V
V <sub>CEO</sub>	Collector-Emitter Voltage	- 25	V
V <sub>EBO</sub>	Emitter-Base Voltage	- 8	V
I <sub>C</sub>	Collector Current (DC)	- 5	Α
I <sub>CP</sub>	Collector Peck Current (Pulse)	- 10	Α
I <sub>B</sub>	Base Current	- 1	Α
P <sub>C</sub>	Collector Dissipation (T <sub>C</sub> = 25°C)	12.5	W
	Collector Dissipation (T <sub>a</sub> = 25°C)	1.4	W
TJ	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	- 65 ~ 150	°C

### **Electrical Characteristics** $T_C=25$ °C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
V <sub>CEO</sub> (sus)	* Collector-Emitter Sustaining Voltage	$I_C = -10 \text{mA}, I_B = 0$	-25		V
I <sub>CBO</sub>	Collector Cut-off Current	$V_{CB} = -40V, I_{E} = 0$		-100	nA
I <sub>EBO</sub>	Emitter Cut-off Current	$V_{EBO} = -8V, I_{C} = 0$		-100	nA
h <sub>FE</sub>	* DC Current Gain	$V_{CE} = -1V, I_{C} = -500mA$	70		
		$V_{CE} = -1V, I_{C} = -2A$	45	180	
		$V_{CE} = -2V, I_{C} = -5A$	10		
V <sub>CE</sub> (sat)	* Collector-Emitter Saturation Voltage	I <sub>C</sub> = - 500mA, I <sub>B</sub> = - 50mA		-0.3	V
		$I_C = -2A$ , $I_B = -200mA$		-0.75	V
		I <sub>C</sub> = -5A, I <sub>B</sub> = -1A		-1.8	V
V <sub>BE</sub> (sat)	* Base-Emitter Saturation Voltage	I <sub>C</sub> = - 5A, I <sub>B</sub> = - 1A		-2.5	V
V <sub>BE</sub> (on)	* Base-Emitter On Voltage	V <sub>CE</sub> = - 1V, I <sub>C</sub> = - 2A		-1.6	V
f <sub>T</sub>	Current Gain Bandwidth Product	V <sub>CE</sub> = - 10V, I <sub>C</sub> = - 100mA	65		MHz
C <sub>ob</sub>	Output Capacitance	$V_{CB} = -10V, I_{E} = 0, f = 0.1MHz$		120	pF

<sup>\*</sup> Pulse Test: PW≤300μs, Duty Cycle≤2%

## **Typical Characteristics**

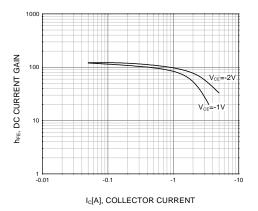


Figure 1. DC current Gain

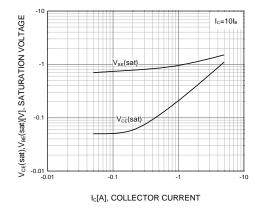


Figure 2. Base-Emitter Saturation Voltage Collector-Emitter Saturation Voltage

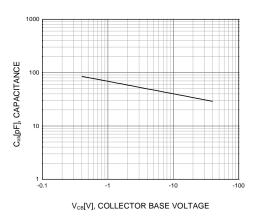


Figure 3. Collector Output Capacitance

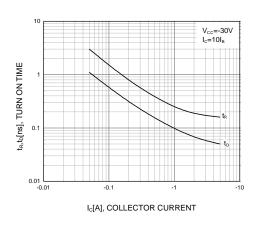


Figure 4. Turn On Time

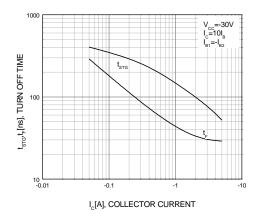


Figure 5. Turn Off Time

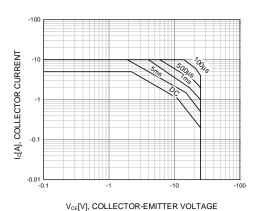


Figure 6. Safe Operating Area

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# Typical Characteristics (Continued)

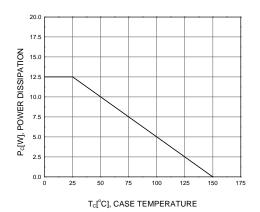
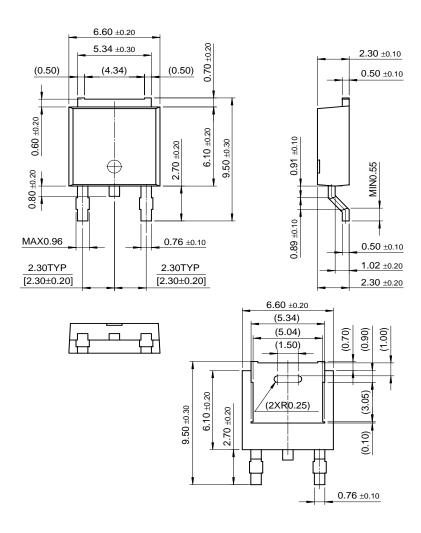


Figure 7. Power Derating

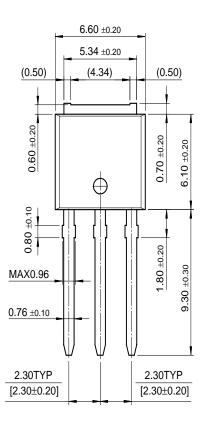
## **Package Dimensions**

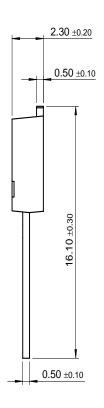
## D-PAK



## Package Dimensions (Continued)

## I-PAK







Dimensions in Millimeters

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CoolFET™	FASTr™	MicroFET™	PowerTrench <sup>®</sup>	SuperSOT™-6
$CROSSVOLT^{TM}$	FRFET™	MicroPak™	QFET™	SuperSOT™-8
DOME™	GlobalOptoisolator™	MICROWIRE™	QS™	SyncFET™
EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic™
E <sup>2</sup> CMOS™	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	$I^2C^{TM}$	$OCX^{TM}$	RapidConfigure™	UHC™
Across the board. Around the world.™		OCXPro™	RapidConnect™	UltraFET <sup>®</sup>
The Power Franchise™		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	VCX <sup>TM</sup>
Programmable Active Droop™		OPTOPLANAR™	SMART START™	

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